MGV252010S2R2M-10

PHYSICAL DIMENSIONS:

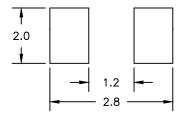
0.20

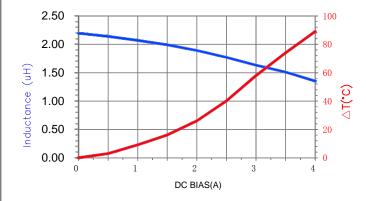
B 2.00 ± 0.20

C 1.00 Max.

 $D = 0.60 \pm 0.30$

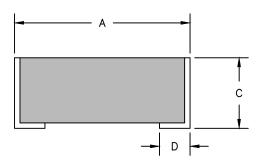
LAND PATTERNS FOR REFLOW SOLDERING



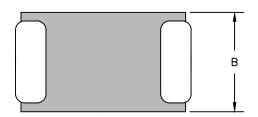


ELECTRICAL SPECIFICATION @ 25°C

	Min	Norm	Max
INDUCTANCE (uH) L @ 1MHz/1mA ±20%	1.76	2.20	2.64
DCR (Ω)		0.088	0.110
Saturation Current Isat (A)		3.30	3.00
Heating Current Irms (A)		2.40	2.10







NOTES:

- 1. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. OPERATING TEMPERATURE RANGE: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$.
- 4. STORAGE TEMPERATURE RANGE: -50°C ~ +125°C .
- 5. ISat MEANS THAT MAX DC CURRENT WILL CAUSE A PROXIMATELY 30% INDUCTANCE REDUCTION FROM INITIAL VALUE.
- 6. Irms MEANS THAT MAX DC CURRENT WILL CAUSE PROXIMATELY 40°C TEMPERATURE RISE FROM 25±5°C AMBIENT.

	DIMENSIONS ARE IN mm.			This print is the property of Laird			
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				with the understanding that no		Lair	
				copies shall be made without the written consent of Laird Tech. All	1	LCIII 1	
				rights to design or invention are	_		
				reserved.			
				PROJECT/PART NUMBER:	REV	PART TYPE:	DRAWN BY:
				MGV252010S2R2M-10	l A	POWER	QIU
				10 12 02 0 10 02 11 2 W		INDUCTOR	
				F 06708717 F	ALE: N	TS SHEET:	
Α	ORIGINAL DRAFT	06/08/17	QIU		OL #		of 1
REV	DESCRIPTION	DATE	INT	MGV252010S2R2M-10-A	,	- '	01 1